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PCN #140

Notification Date:
13 August 2012

Product / Process Change Notice

Parts Affected:
CPD06 wafer process; 3 Amp, glass passivated, general purpose rectifiers.

Extent of Change:
Anode pad size was increased from 66 x 66 mils to 77 x 77 mils.

Reason for Change:
To increase the bonding pad area to allow more process latitude in the assembly process; larger bonding pad area provides for use of larger bond wires or clips. The only change was the increase in the bonding pad area; no other changes in the wafer diffusion process were performed.

Effect of Change:
This change does not affect the electrical characteristics of any device.

Qualification:
Standard evaluation and qualifications completed resulting in no performance differences compared to current product.

Effective Date of Change:
Q3 2011.

Sample Availability:
Please contact Salesperson or Manufacturer's Representative.

Part Numbers Affected
CMR3-02
CMR3-04
CMR3-06
CMR3-08
CMR3-10
CMR3-11
1N5400 thru 1N5408
1N5550 thru 1N5554
CPD06-CMR3-06-CT
CPD06-CMR3-06-WN
CPD06-1N5406-WN
CPD06-1N5554-WN